

Trench gate field-stop IGBT, M series 650 V, 10 A low loss

Datasheet - production data

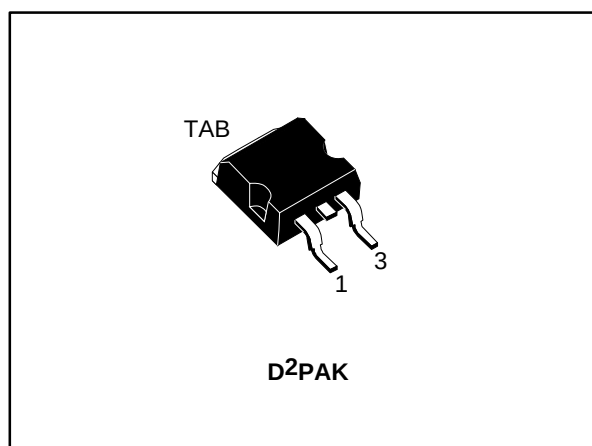
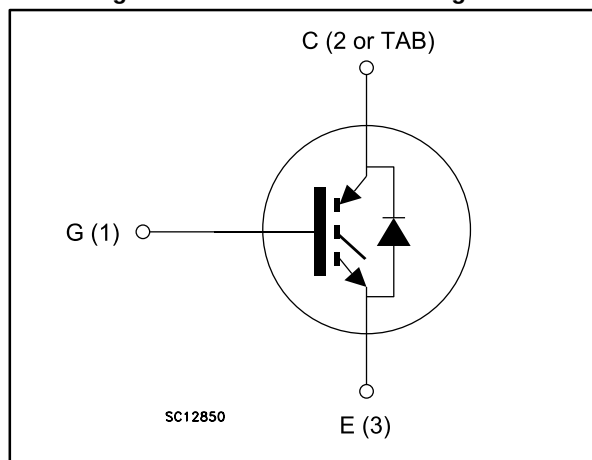


Figure 1: Internal schematic diagram



Features

- 6 μ s of short-circuit withstand time
- $V_{CE(sat)} = 1.55$ V (typ.) @ $I_C = 10$ A
- Tight parameters distribution
- Safer paralleling
- Low thermal resistance
- Soft and very fast recovery antiparallel diode

Applications

- Motor control
- UPS
- PFC

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the M series of IGBTs, which represent an optimum compromise in performance to maximize the efficiency of inverter systems where low-loss and short-circuit capability are essential. Furthermore, a positive $V_{CE(sat)}$ temperature coefficient and tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packaging
STGB10M65DF2	G10M65DF2	D ² PAK	Tape and reel

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$)	650	V
I_C	Continuous collector current at $T_C = 25\text{ °C}$	20	A
	Continuous collector current at $T_C = 100\text{ °C}$	10	
$I_{CP}^{(1)}$	Pulsed collector current	40	A
V_{GE}	Gate-emitter voltage	± 20	V
I_F	Continuous forward current at $T_C = 25\text{ °C}$	20	A
	Continuous forward current at $T_C = 100\text{ °C}$	10	
$I_{FP}^{(1)}$	Pulsed forward current	40	A
P_{TOT}	Total dissipation at $T_C = 25\text{ °C}$	115	W
T_{STG}	Storage temperature range	- 55 to 150	°C
T_J	Operating junction temperature	- 55 to 175	

Notes:

⁽¹⁾Pulse width limited by maximum junction temperature.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	1.3	°C/W
R_{thJC}	Thermal resistance junction-case diode	2.08	
R_{thJA}	Thermal resistance junction-ambient	62.5	

2 Electrical characteristics

$T_C = 25\text{ °C}$ unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}$, $I_C = 2\text{ mA}$	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}$, $I_C = 10\text{ A}$		1.55	2.0	V
		$V_{GE} = 15\text{ V}$, $I_C = 10\text{ A}$, $T_J = 125\text{ °C}$		1.9		
		$V_{GE} = 15\text{ V}$, $I_C = 10\text{ A}$, $T_J = 175\text{ °C}$		2.1		
V_F	Forward on-voltage	$I_F = 10\text{ A}$		1.5		V
		$I_F = 10\text{ A}$, $T_J = 125\text{ °C}$		1.3		
		$I_F = 10\text{ A}$, $T_J = 175\text{ °C}$		1.2		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 250\text{ }\mu\text{A}$	5	6	7	V
I_{CES}	Collector cut-off current	$V_{GE} = 0\text{ V}$, $V_{CE} = 650\text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current	$V_{CE} = 0\text{ V}$, $V_{GE} = \pm 20\text{ V}$			250	μA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GE} = 0\text{ V}$	-	840	-	pF
C_{oes}	Output capacitance		-	63	-	
C_{res}	Reverse transfer capacitance		-	16	-	
Q_g	Total gate charge	$V_{CC} = 400\text{ V}$, $I_C = 10\text{ A}$, $V_{GE} = 15\text{ V}$ (see Figure 30 : "Gate charge test circuit")	-	28	-	nC
Q_{ge}	Gate-emitter charge		-	6	-	
Q_{gc}	Gate-collector charge		-	12	-	

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$, $I_C = 10\text{ A}$, $V_{GE} = 15\text{ V}$, $R_G = 22\ \Omega$ (see Figure 29: "Test circuit for inductive load switching")	-	19	-	ns
t_r	Current rise time		-	7.4	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1086	-	A/ μ s
$t_{d(off)}$	Turn-off-delay time		-	91	-	ns
t_f	Current fall time		-	92	-	ns
$E_{on(1)}$	Turn-on switching losses		-	0.12	-	mJ
$E_{off(2)}$	Turn-off switching losses		-	0.27	-	mJ
E_{ts}	Total switching losses		-	0.39	-	mJ
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$, $I_C = 10\text{ A}$, $V_{GE} = 15\text{ V}$, $R_G = 22\ \Omega$ $T_J = 175\text{ }^\circ\text{C}$ (see Figure 29: "Test circuit for inductive load switching")	-	18	-	ns
t_r	Current rise time		-	9	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	890	-	A/ μ s
$t_{d(off)}$	Turn-off-delay time		-	90	-	ns
t_f	Current fall time		-	45	-	ns
E_{on}	Turn-on switching losses		-	0.26	-	mJ
E_{off}	Turn-off switching losses		-	0.4	-	mJ
E_{ts}	Total switching losses		-	0.66	-	mJ
t_{sc}	Short-circuit withstand time	$V_{CC} \leq 400\text{ V}$, $V_{GE} = 15\text{ V}$, $T_{Jstart} = 150\text{ }^\circ\text{C}$	6		-	μ s

Notes:

(1)Energy losses include reverse recovery of the diode.

(2)Turn-off losses also include the tail of the collector current.

Table 7: Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 10\text{ A}$, $V_R = 400\text{ V}$, $V_{GE} = 15\text{ V}$ (see Figure 29: "Test circuit for inductive load switching") $di/dt = 1000\text{ A}/\mu\text{s}$	-	96		ns
Q_{rr}	Reverse recovery charge		-	373		nC
I_{rrm}	Reverse recovery current		-	13		A
dl_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	661		A/ μ s
E_{rr}	Reverse recovery energy		-	52		mJ
t_{rr}	Reverse recovery time	$I_F = 10\text{ A}$, $V_R = 400\text{ V}$, $V_{GE} = 15\text{ V}$, $T_J = 175\text{ }^\circ\text{C}$ (see Figure 29: "Test circuit for inductive load switching") $di/dt = 1000\text{ A}/\mu\text{s}$	-	201		ns
Q_{rr}	Reverse recovery charge		-	1352		nC
I_{rrm}	Reverse recovery current		-	19		A
dl_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	405		A/ μ s
E_{rr}	Reverse recovery energy		-	150		mJ

2.1 Electrical characteristics (curves)

Figure 2: Power dissipation vs. case temperature

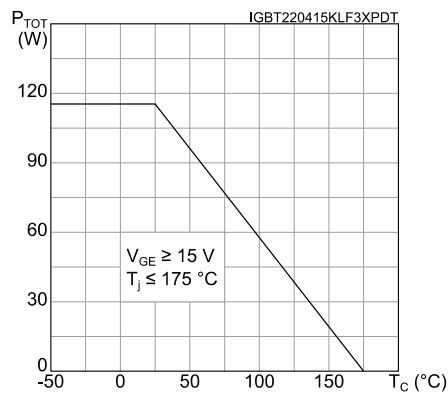


Figure 3: Collector current vs. case temperature

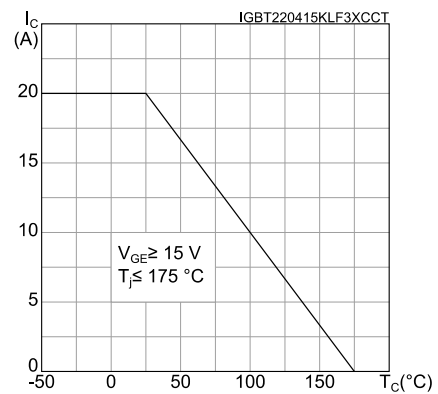


Figure 4: Output characteristics (T_J = 25 °C)

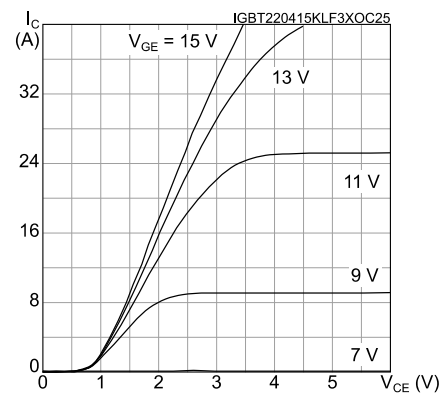


Figure 5: Output characteristics (T_J = 175 °C)

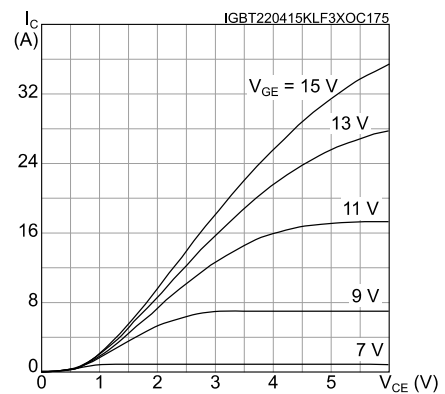


Figure 6: V_{CE(sat)} vs. junction temperature

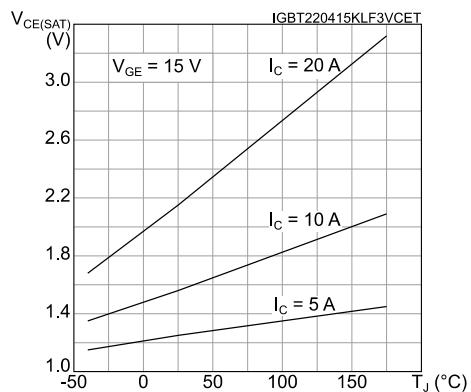


Figure 7: V_{CE(sat)} vs. collector current

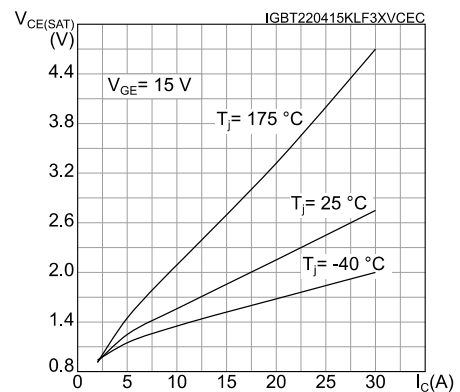


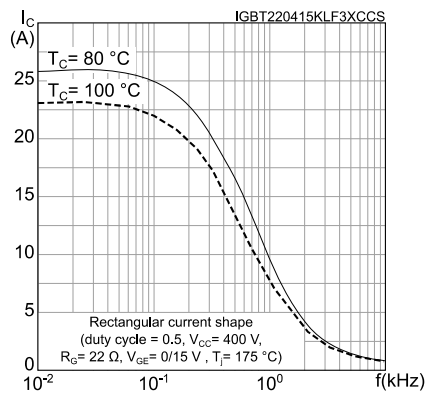
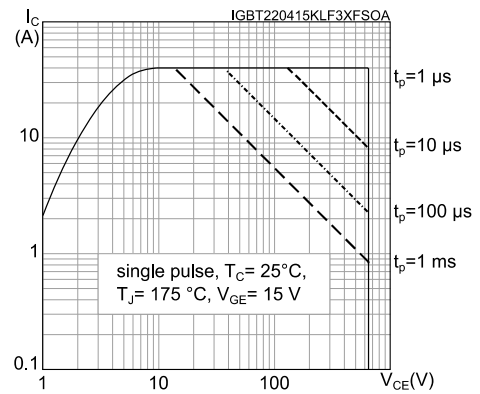
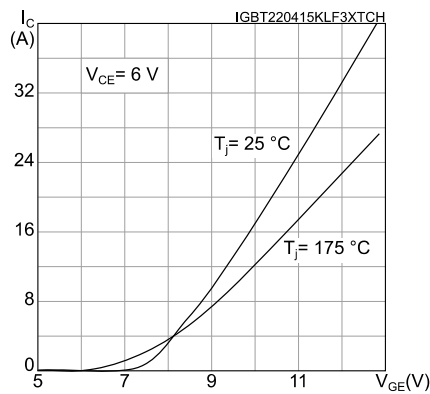
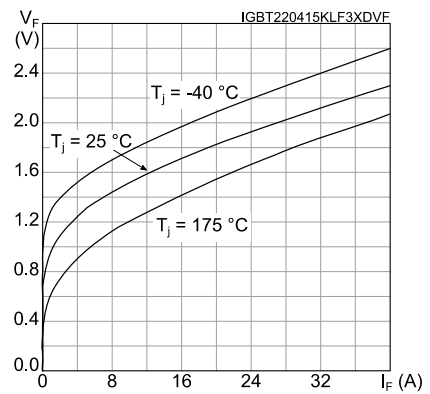
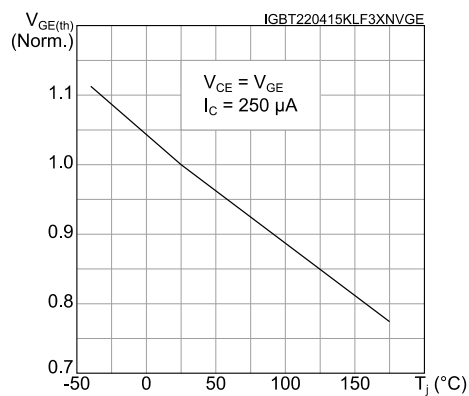
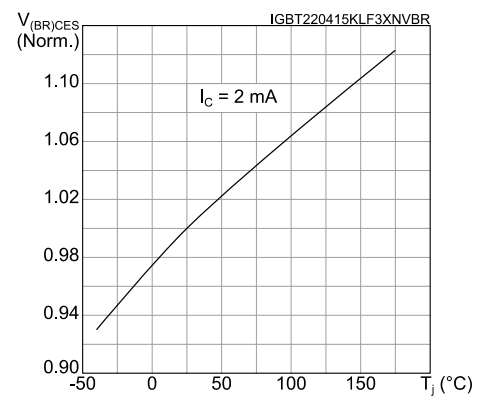
Figure 8: Collector current vs. switching frequency**Figure 9: Forward bias safe operating area****Figure 10: Transfer characteristics****Figure 11: Diode VF vs. forward current****Figure 12: Normalized V_GE(th) vs. junction temperature****Figure 13: Normalized V(BR)CES vs. junction temperature**

Figure 14: Capacitance variations

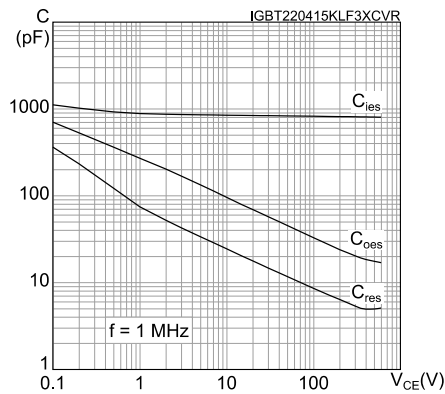


Figure 15: Gate charge vs. gate-emitter voltage

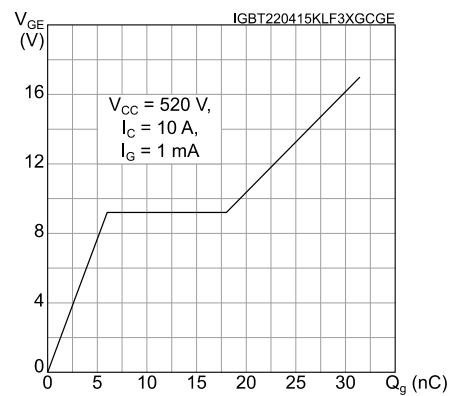


Figure 16: Switching loss vs. collector current

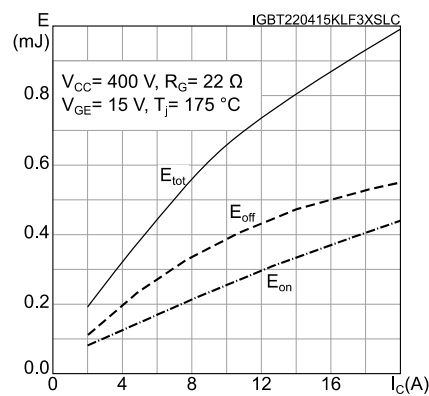


Figure 17: Switching loss vs. gate resistance

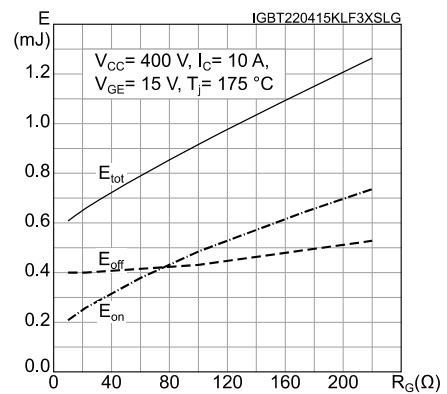


Figure 18: Switching loss vs. temperature

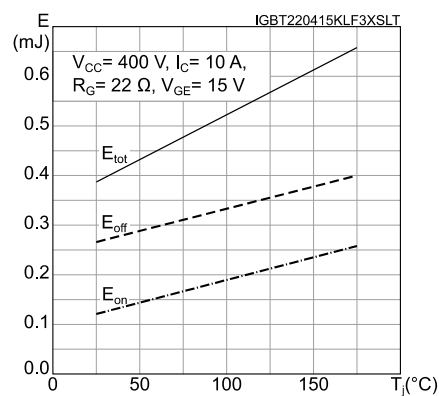


Figure 19: Switching loss vs. collector emitter voltage

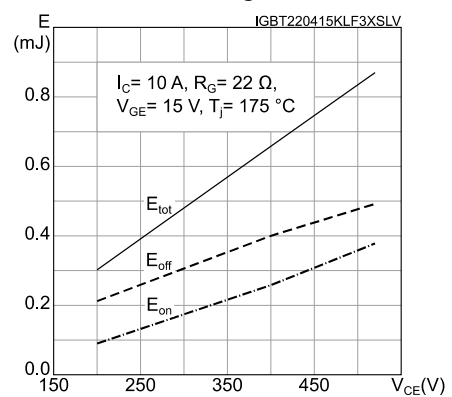


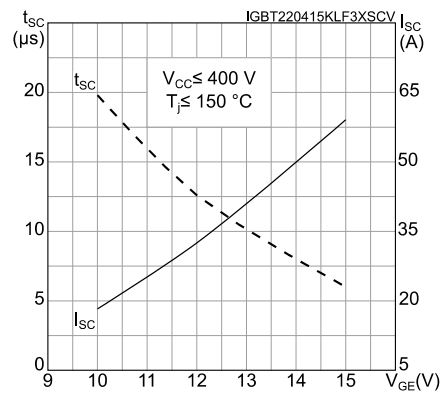
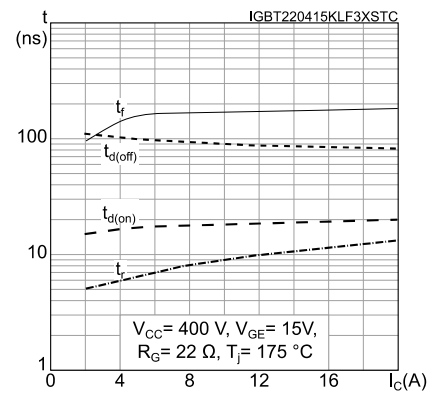
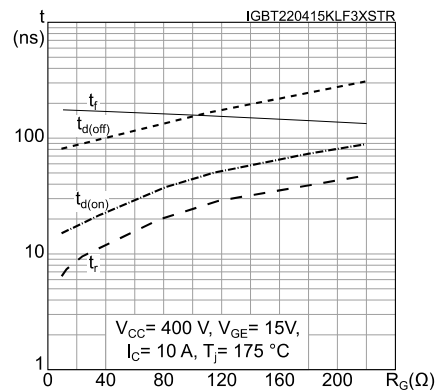
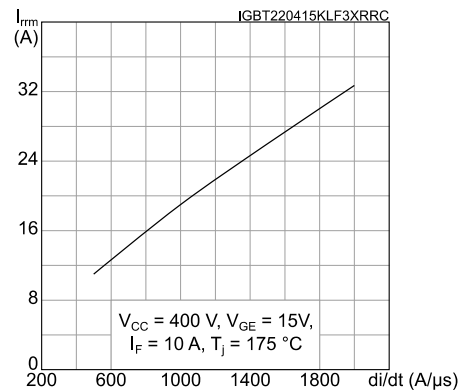
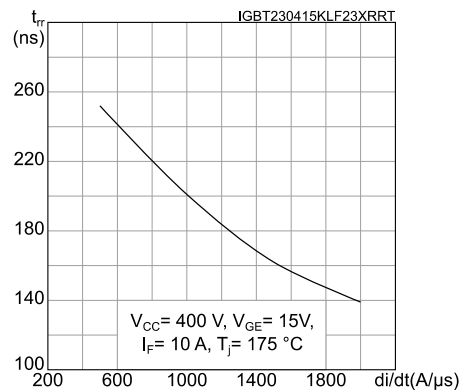
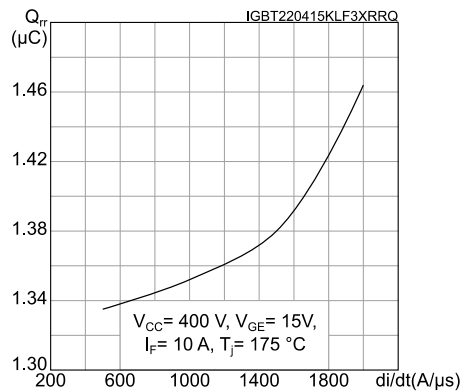
Figure 20: Short-circuit time and current vs. V_{GE}**Figure 21: Switching times vs. collector current****Figure 22: Switching times vs. gate resistance****Figure 23: Reverse recovery current vs. diode current slope****Figure 24: Reverse recovery time vs. diode current slope****Figure 25: Reverse recovery charge vs. diode current slope**

Figure 26: Reverse recovery energy vs. diode current slope

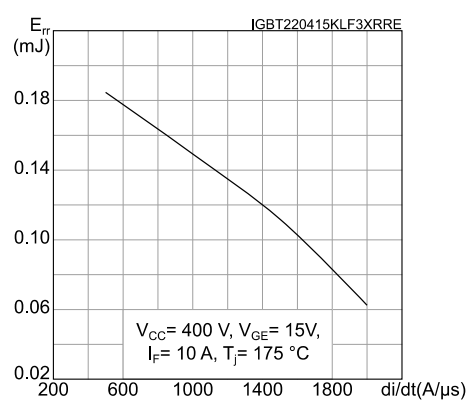


Figure 27: Thermal impedance for IGBT

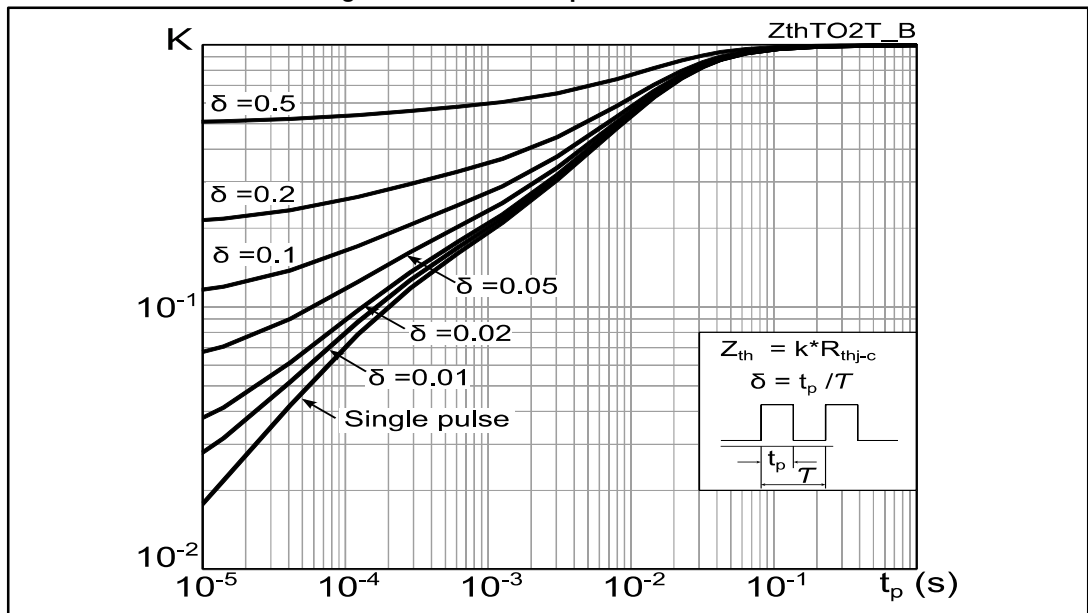
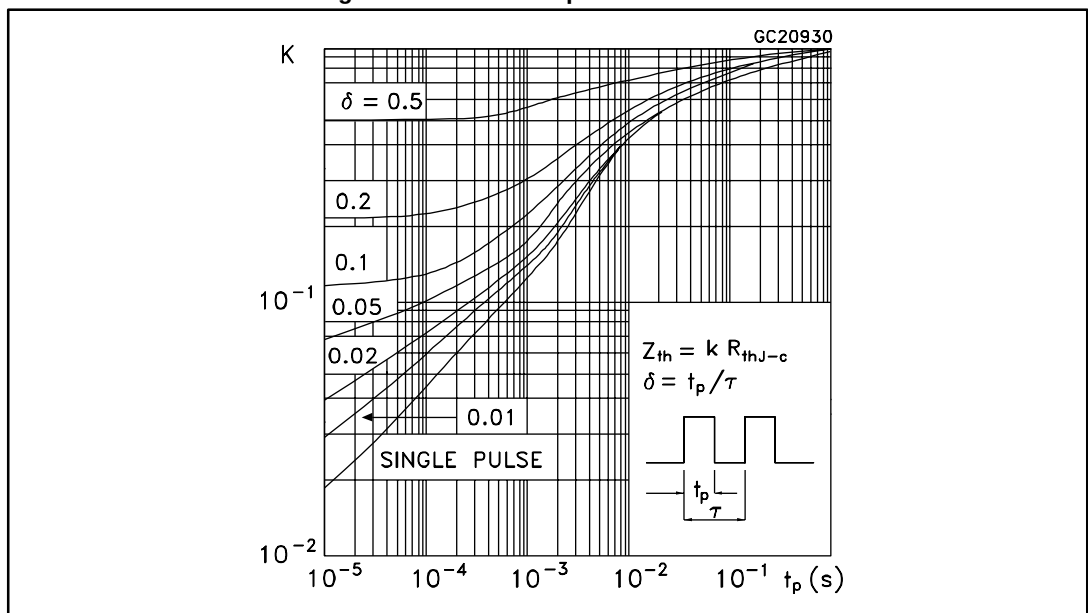


Figure 28: Thermal impedance for diode

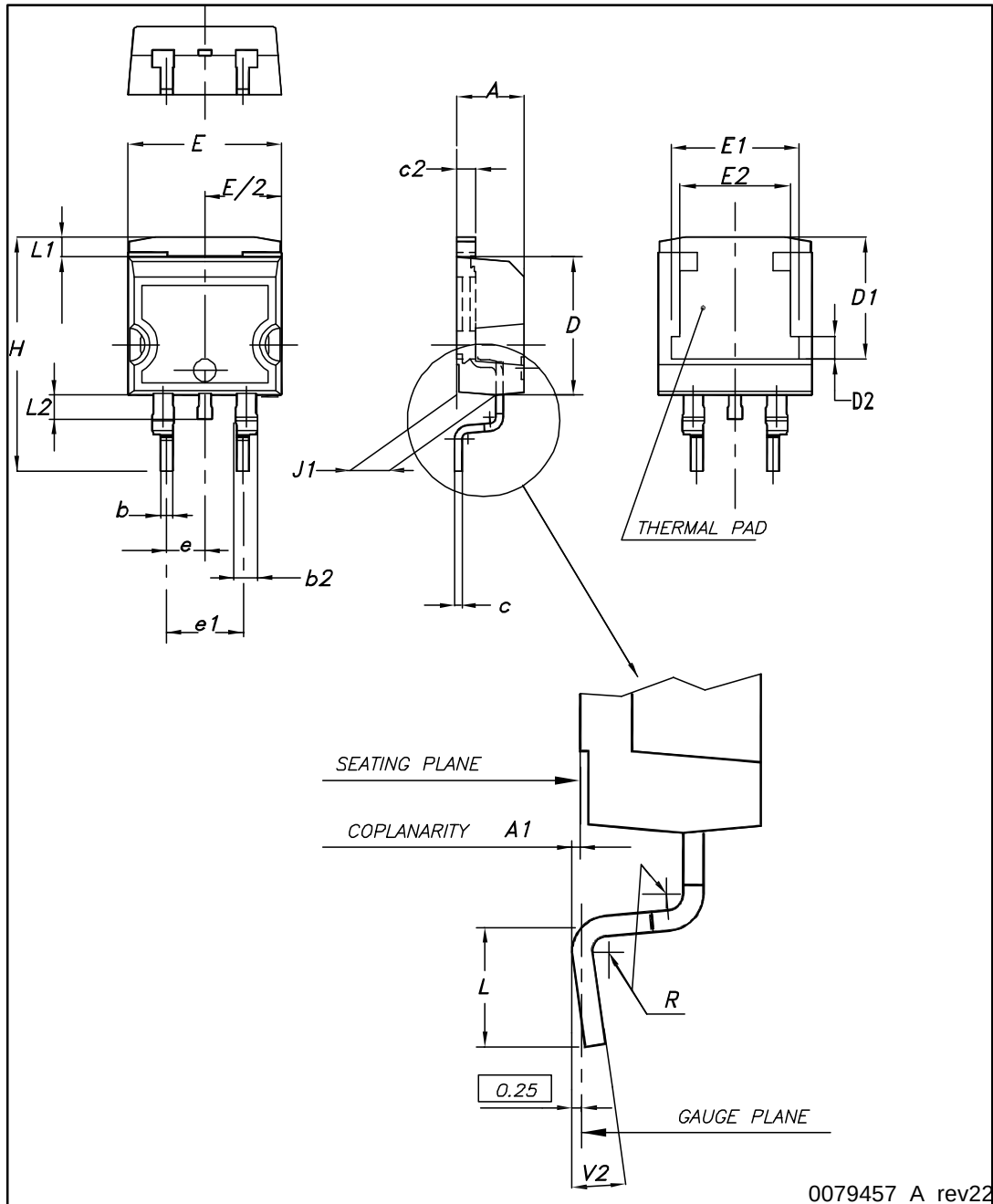


4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 D²PAK package information

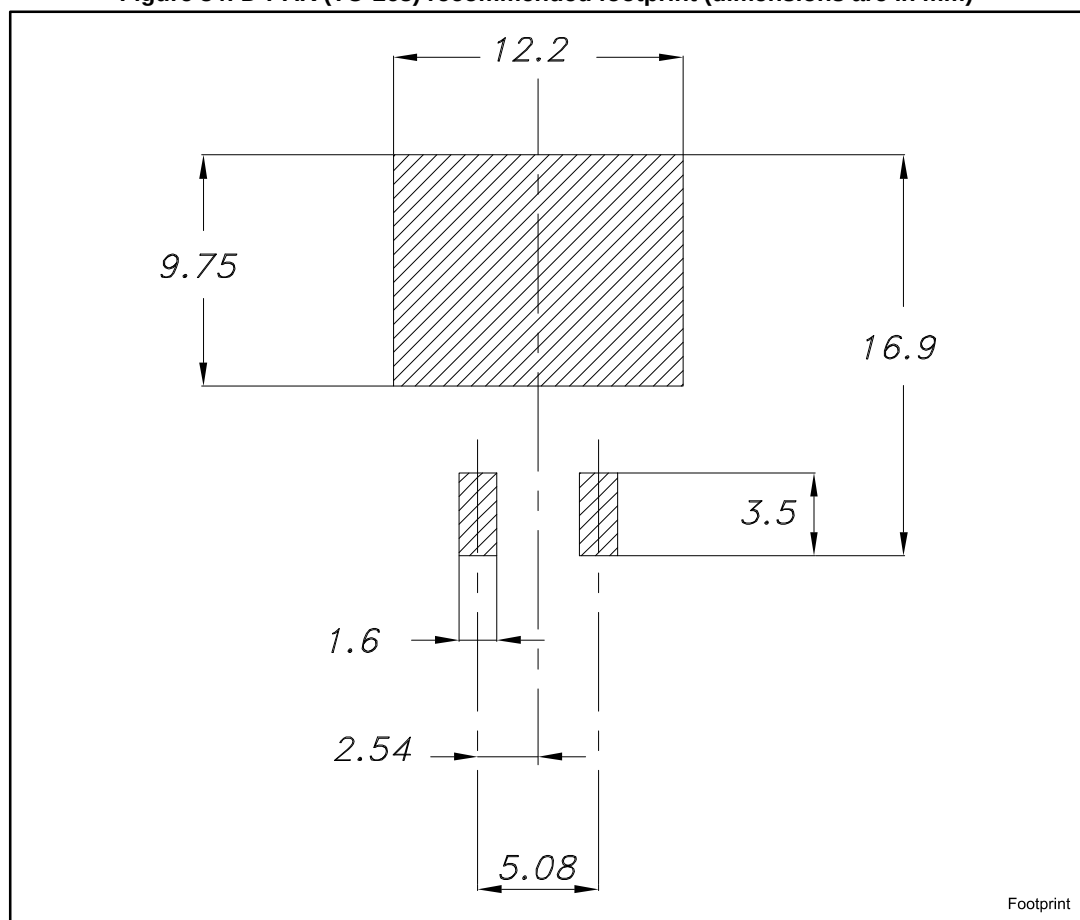
Figure 33: D²PAK (TO-263) type A package outline



0079457_A_rev22

Table 8: D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 34: D²PAK (TO-263) recommended footprint (dimensions are in mm)

4.2 Packing information

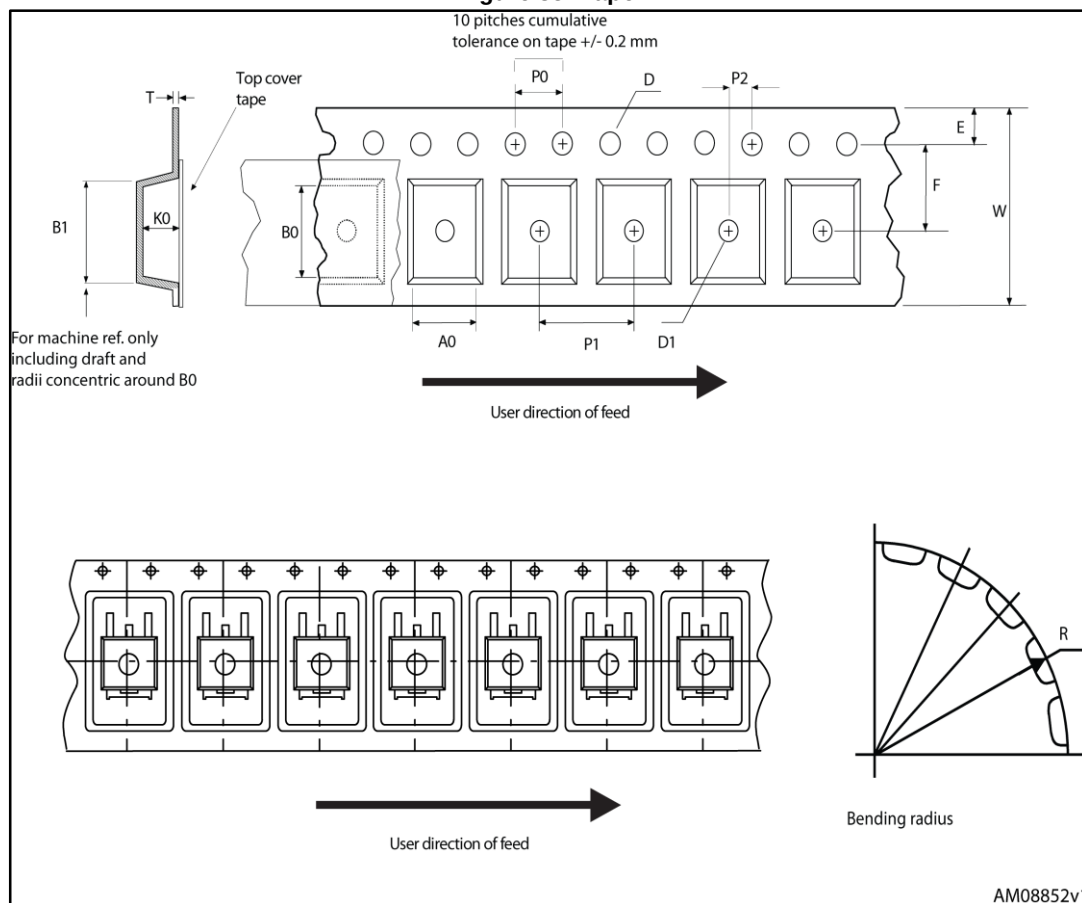
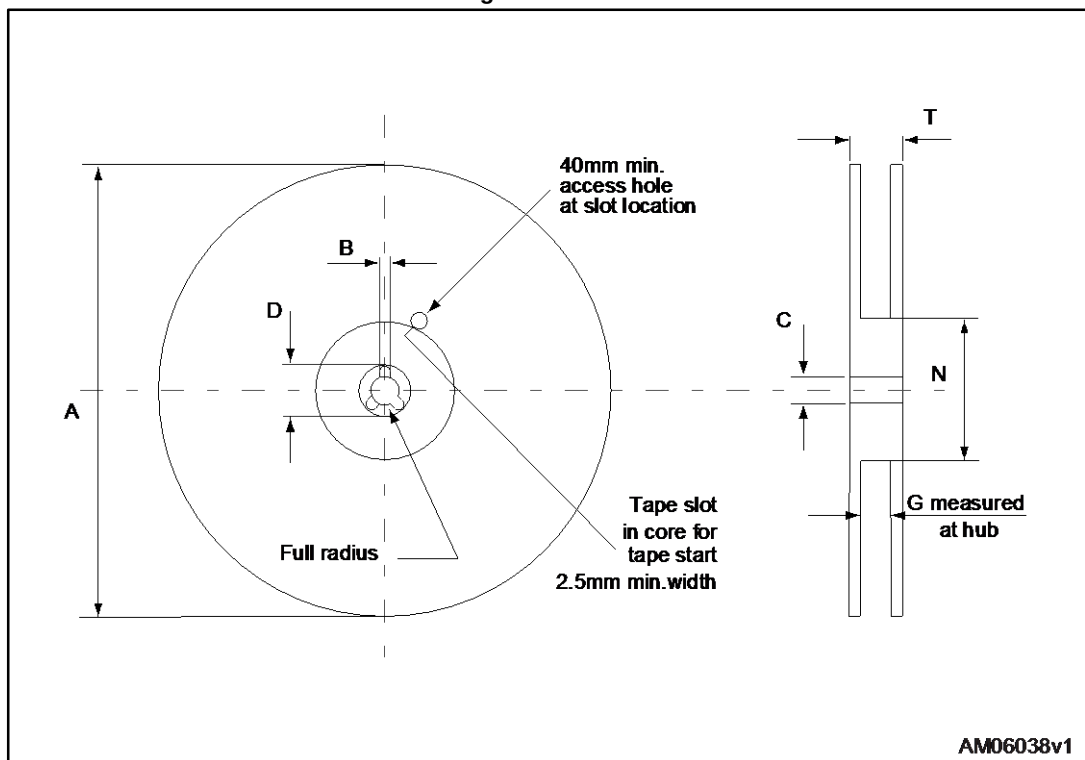
Figure 35: Tape

Figure 36: Reel

Table 9: D²PAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base qty		1000
P2	1.9	2.1	Bulk qty		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
10-Feb-2015	1	First release.
23-Apr-2015	2	Minor text edits throughout document In Section 2 Electrical characteristics: - updated Table 4: Static characteristics - updated Table 5: Dynamic characteristics - updated Table 6: IGBT switching characteristics (inductive load) - updated Table 7: Diode switching characteristics (inductive load) Added Section 2.1 Electrical characteristics (curves)
11-Jun-2015	3	Document status promoted from preliminary to production data.

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